



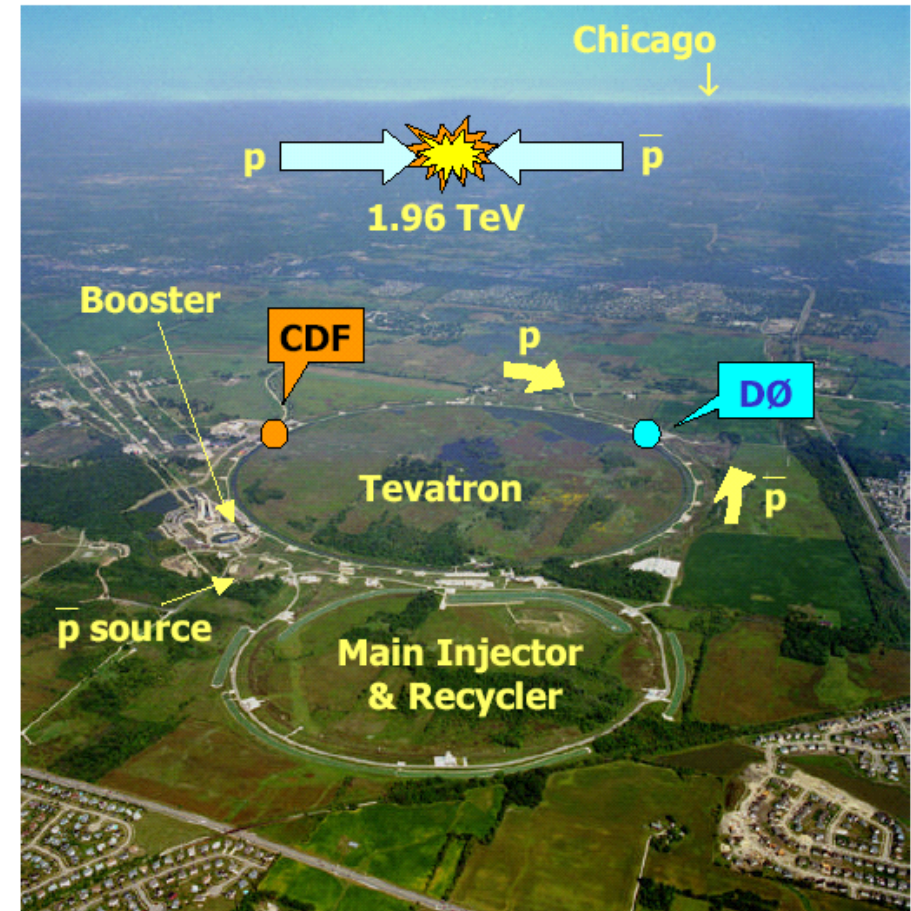
# Radiation hardness experience in CDF/DØ silicon detectors

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Yale University

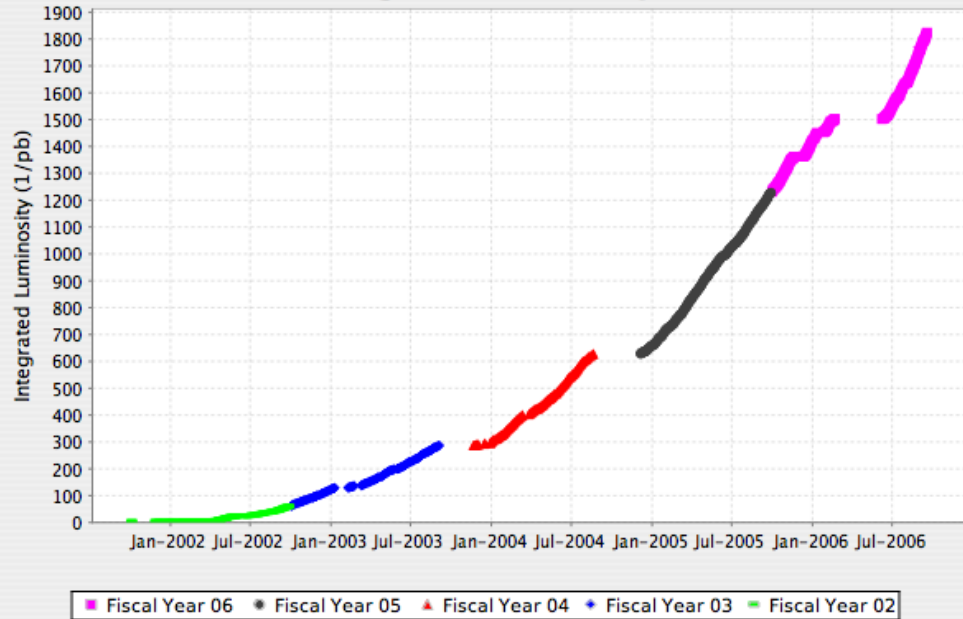
for the CDF & DØ Collaborations

- Run-II energy 1.96 TeV
- Proton-Antiproton collisions
- 36 x 36 bunches
- Bunch spacing 396 ns
- Luminosity goal:
  - $8 \text{ fb}^{-1}$  (*Design*)
  - $4 \text{ fb}^{-1}$  (*Base*)
- Two collider experiments, **CDF** and **DØ**

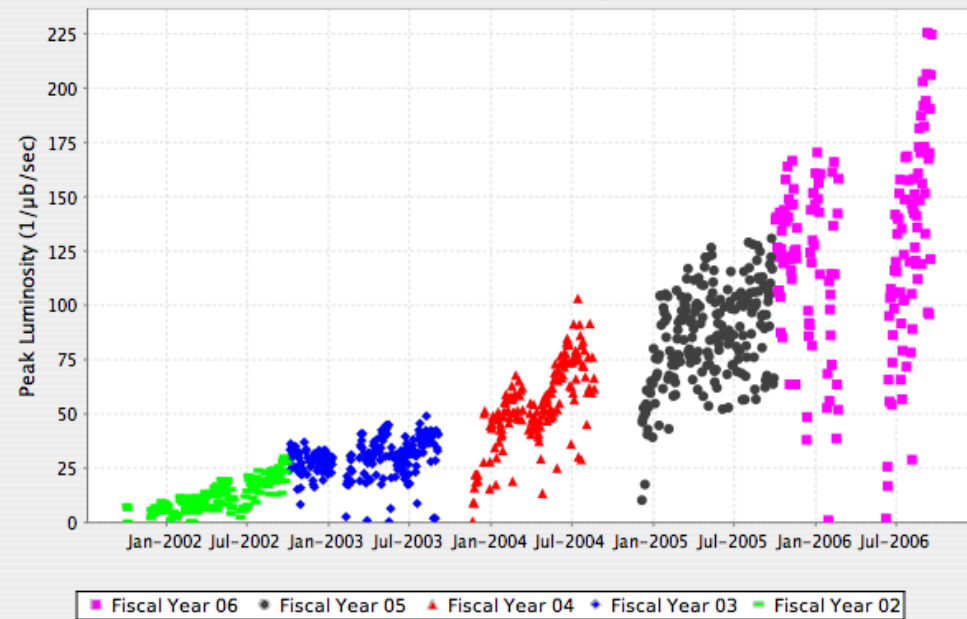


# Tevatron Performance

Integrated Luminosity



Peak Luminosity



**The machine is performing very well !**

Highest instantaneous luminosity :  $229 \cdot 10^{30} \text{ cm}^2 \text{ s}^{-1}$

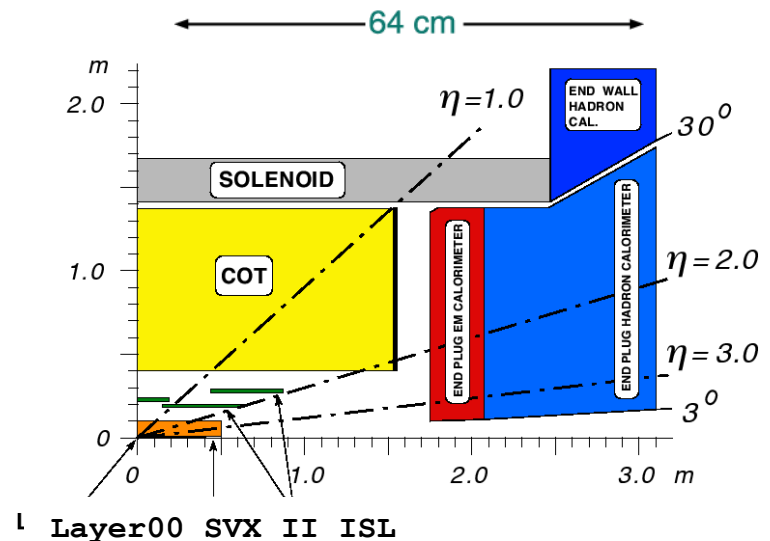
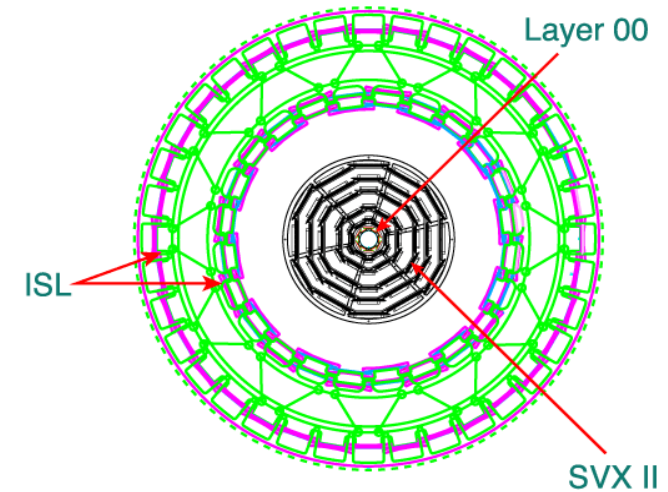
Delivered luminosity /week :  $> 30 \text{ pb}^{-1}$

Delivered luminosity (Run-II) :  $1.8 \text{ fb}^{-1}$

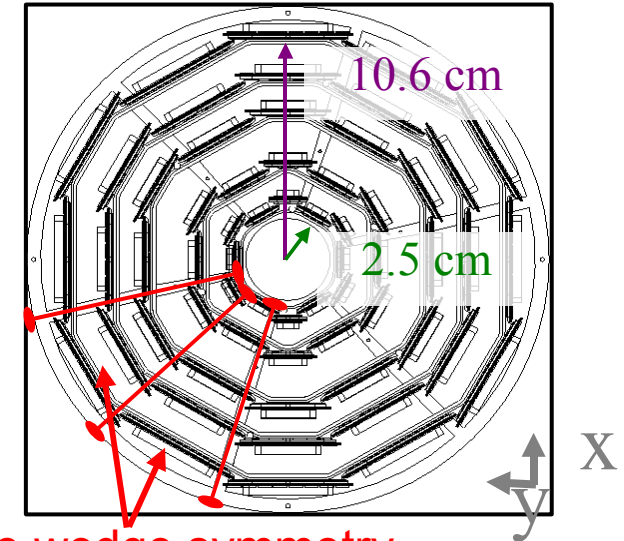
Delivered luminosity (Run-I) :  $\sim 150 \text{ pb}^{-1}$

Tevatron expects to deliver 5 to  $8 \text{ fb}^{-1}$  by the end of Run II

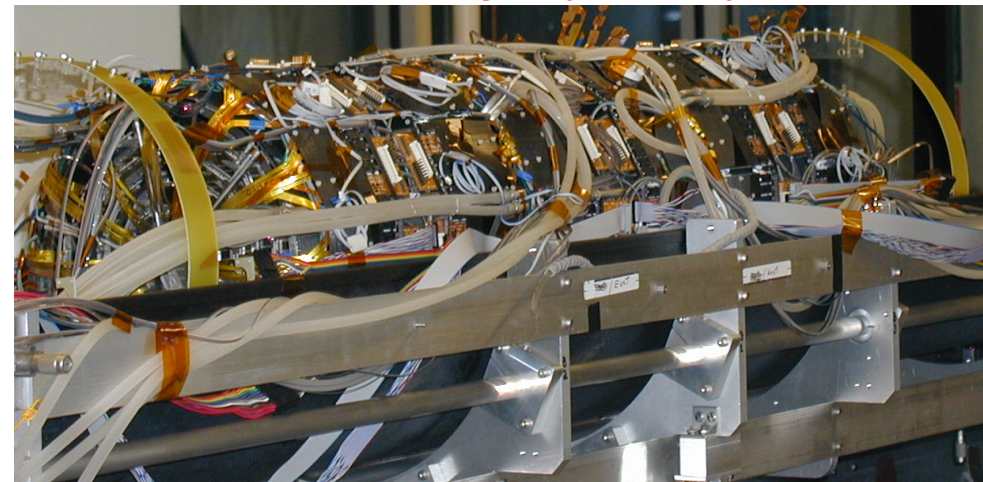
- Versatile Silicon detector
  - Three components: SVX-II, ISL, L00
  - 7-8 layers, 722432 readout channels
  - 7 m<sup>2</sup> of Silicon
  - 3D hit information
- Data used in L2 Trigger (SVT)
  - Deadtimeless chip (SVX3D)
  - Fast parallel readout
  - L1 Accept Rate 35-40 kHz
  - Use Dynamic Pedestal subtraction



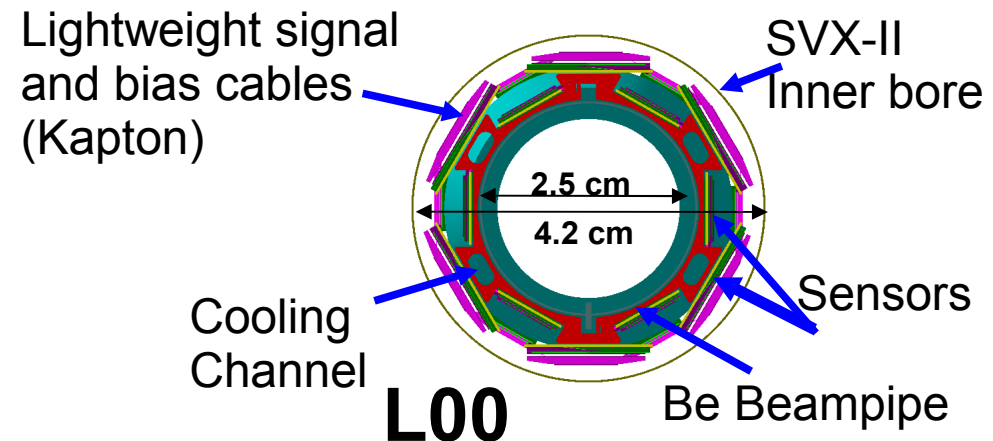
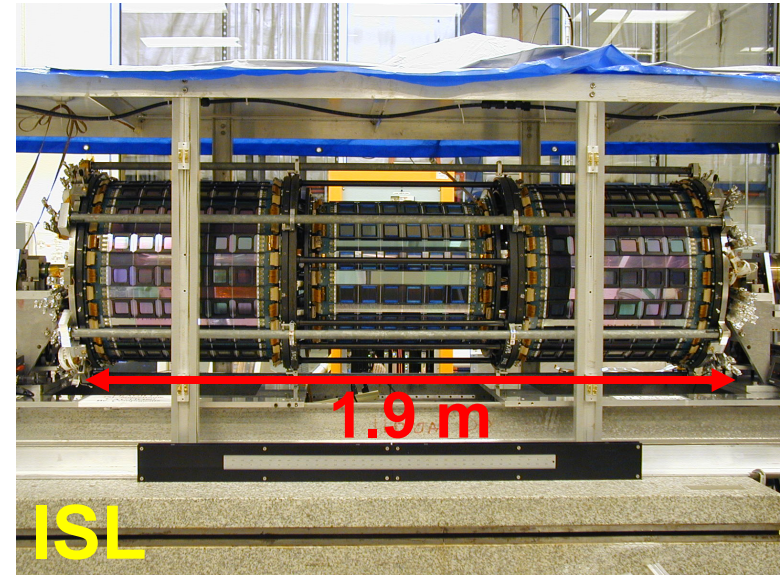
- 6 bulkheads and 5 layers
  - 12 wedges per layer
  - Highly symmetric ( for SVT )
- Double Sided Silicon
  - Layers 0,1,3 with  $r\Phi/rZ$  (Hamamatsu)
  - Layer 2+4 Small Angle Stereo(SAS) (Micron)



Note wedge symmetry

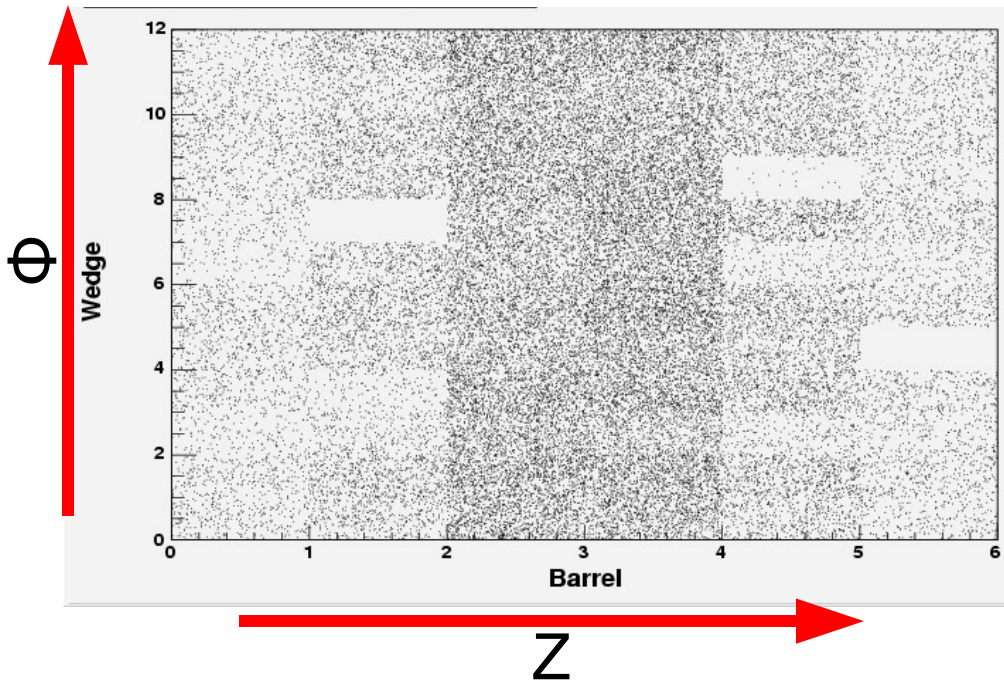


- ISL
  - 2 additional layers
  - SAS Hamamatsu+Micron
  - adds forward coverage up to  $|\eta|=2$
- L00
  - LHC style Silicon
  - single-sided
  - actively cooled
- Both are not part of the trigger

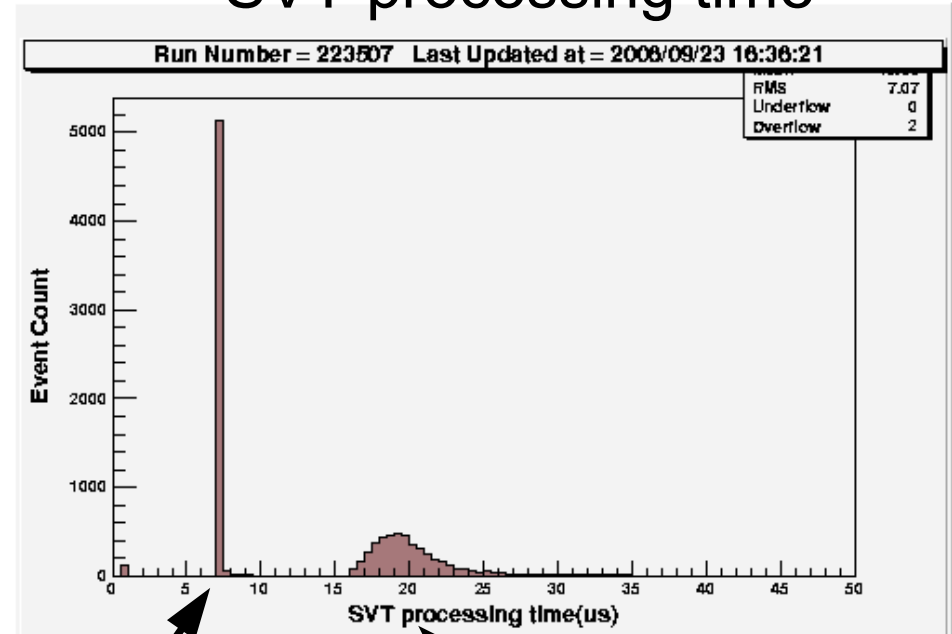


# CDF: Impact of SVT

## SVT coverage



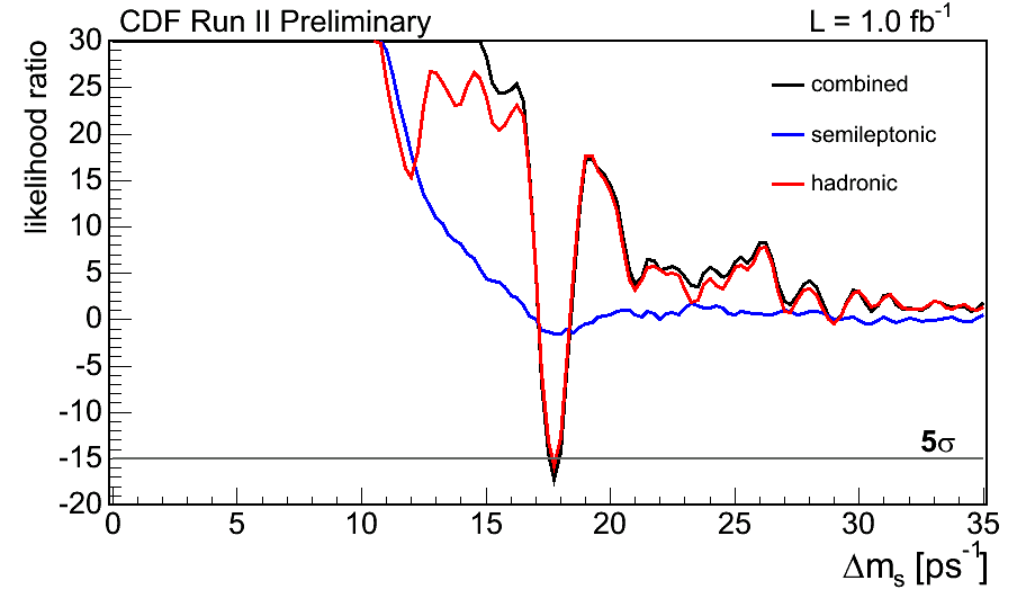
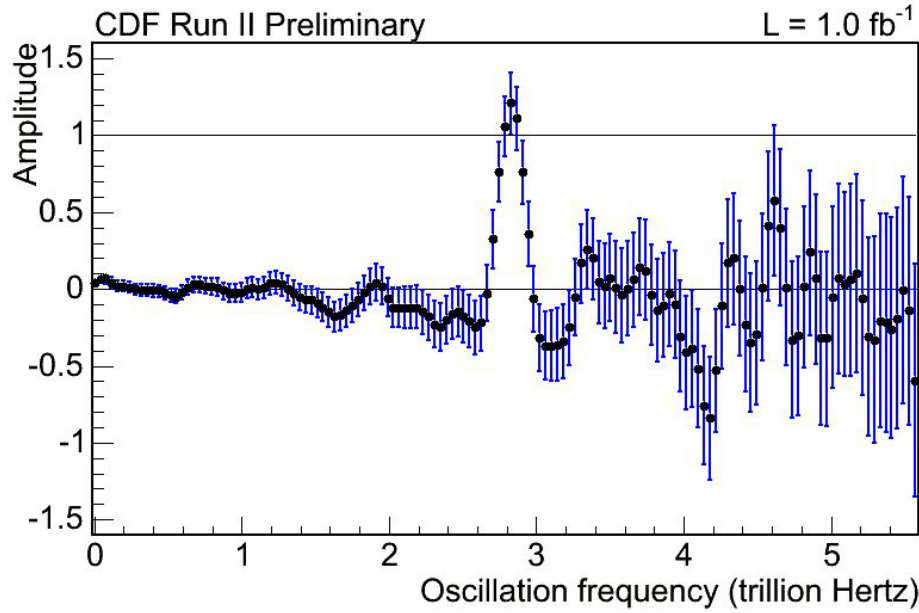
## SVT processing time



No L1 Tracks  
fast abort

SVT processes  
SVX-II data

# CDF's latest result

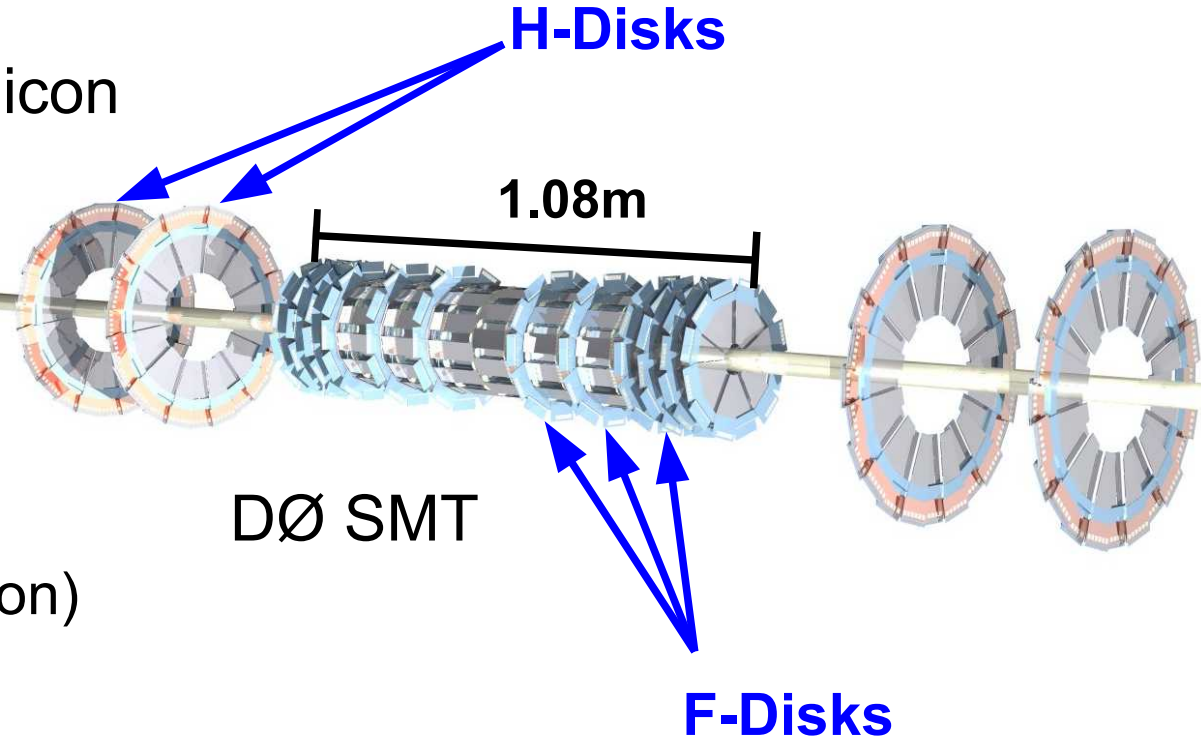


$$\Delta m_s = 17.77 \pm 0.10(\text{stat}) \pm 0.07(\text{sys})$$



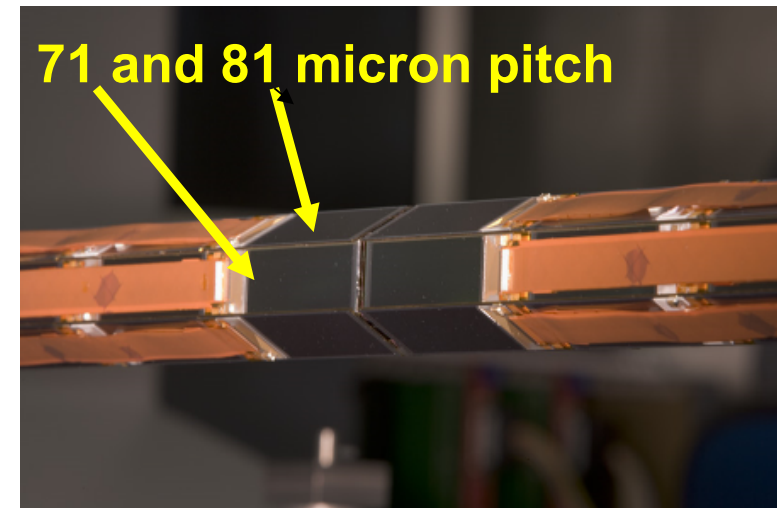
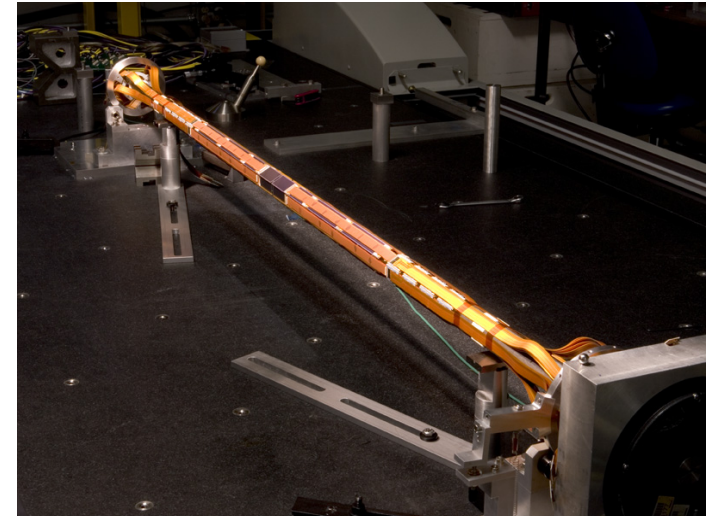
# DØ Silicon Microstrip Tracker

- Single system 3 m<sup>2</sup> of Silicon
  - 6 barrels, 4 layers each
  - 12 F-disks + 4 H-disks
- Layer 1+3



- IN r $\Phi$ /rZ (Micron)
- OUT Single sided (Micron)
- Layer 2+4 SAS (Micron)
- F-Disks SAS (Micron/Eurysis)
- H-Disks SAS (ELMA)
- Used in L2 Trigger ->L1 Accept rate ~ 5 kHz

- Most recent upgrade
- Placed inside Layer 1
- Installed during 2006 Shutdown
- The detector consists of:
  - 48 modules arranged in 6 wedges
  - Module length : 12 and 7 cm
- See D. Tsybychev's talk





# Detector Longevity



For CDF and DØ, radiation damage to the sensors is the main concern for detector longevity.

## **Both experiments define several criteria for the lifetime**

- Inability to deplete the sensors
  - The innermost layers L0 (CDF) & L1 (DØ) are most critical
  - Depletion voltage limit is sensor dependent
- S/N degradation due to radiation damage
  - There is no fixed S/N at which the hit reconstruction will be impossible, things can be recovered by smarter software
  - Impact on L2 trigger efficiency



# CDF & DØ Studies



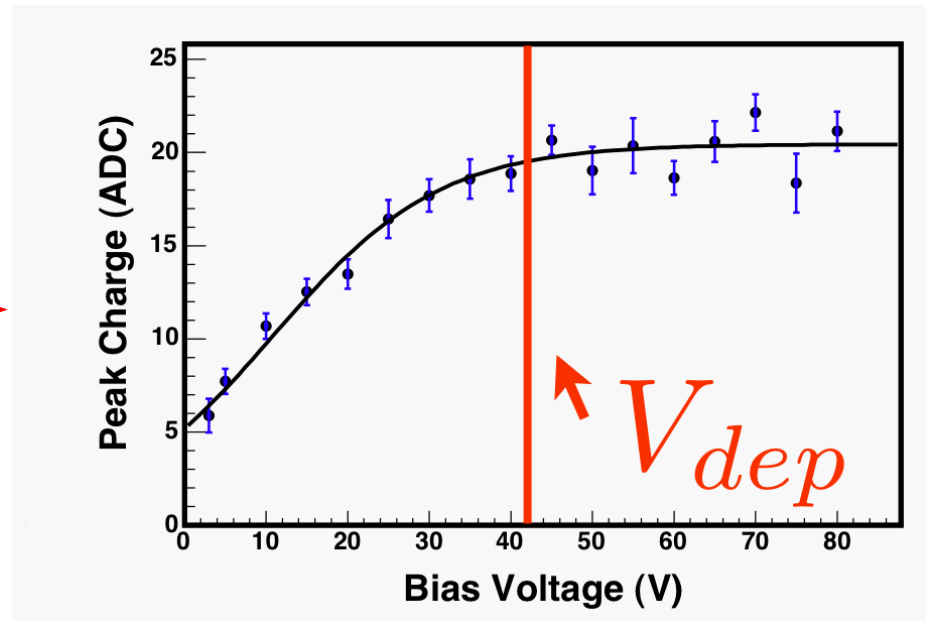
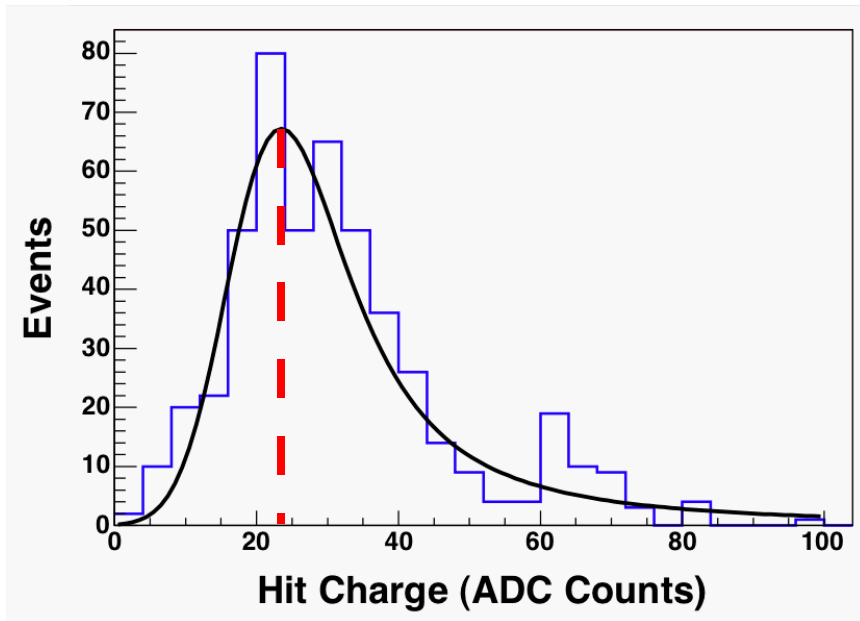
- CDF
  - Depletion voltage measurements (Bias scans)
  - Bias current monitoring
  - S/N measurements using data
- DØ
  - Depletion voltage measurements (Bias scans)
  - Bias current monitoring



# CDF: Depletion Voltage Scan

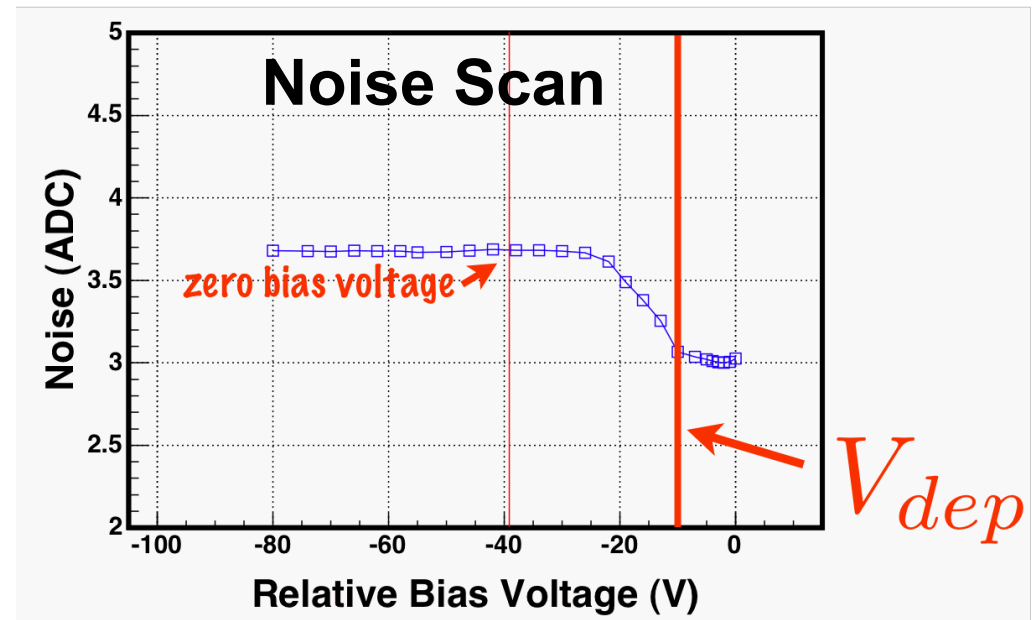
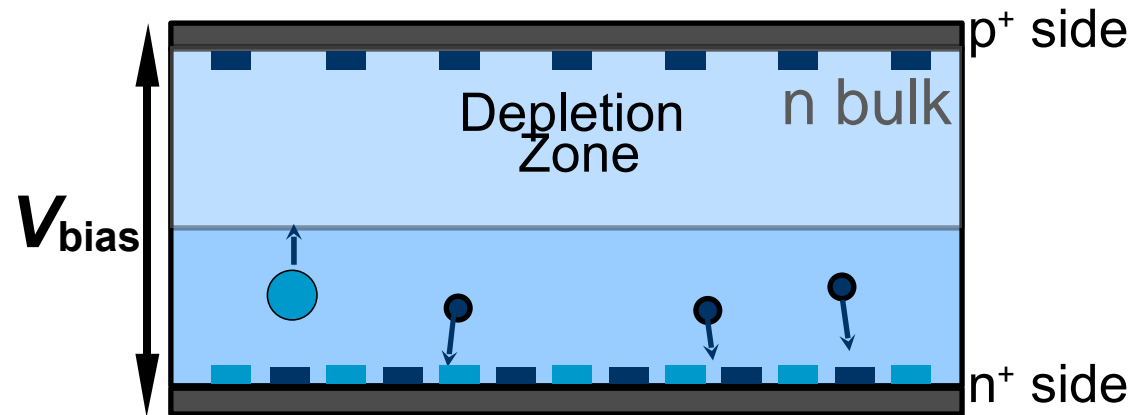


- Method to determine actual depletion voltage of the detector
- Signal scan
  - Requires beam time
- Noise scan
  - Can be done during no beam time
  - Works only with double-sided Silicon
- The maximum bias voltage is limited by the sensor's integrated capacitor
  - The breakdown voltage depends on the sensor type



- Study collected charge of hits on tracks depending on bias voltage
- Fit Landau  $\otimes$  Gaussian to determine the peak for each point
- Depletion voltage  $V_{dep}$  is 95 % amplitude of sigmoid fit

- Use dependence of the n-side noise on the bias voltage
- Depletion voltage derived from minimum in noise.
- Only works for double-sided detectors (SVX-II, ISL)
- Expected to work reliably till type inversion

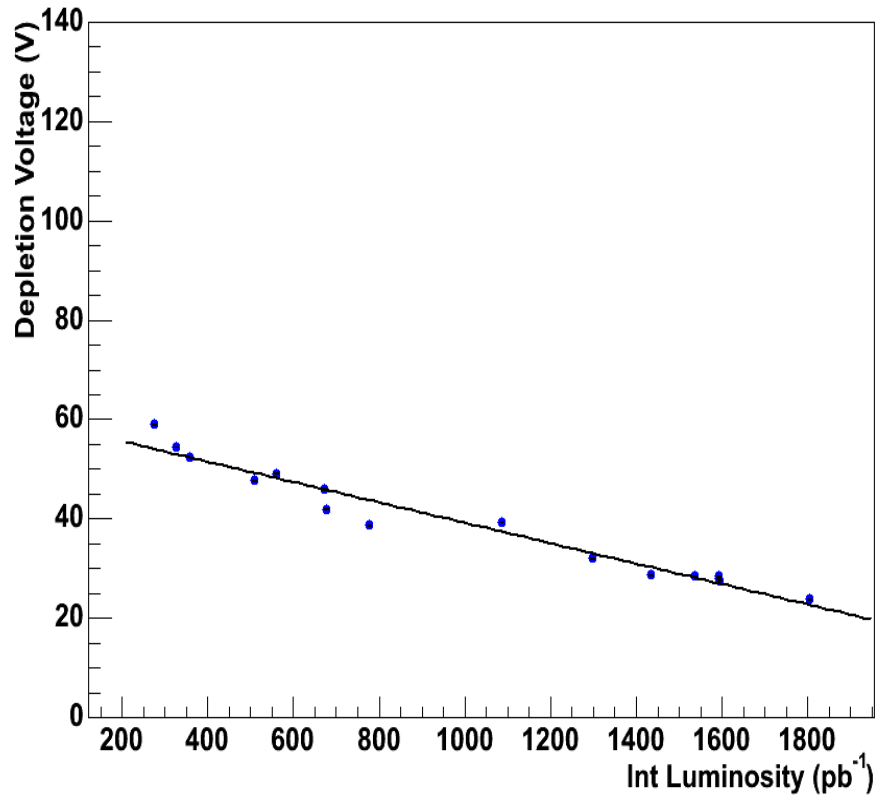




# CDF Depletion Voltage Evolution

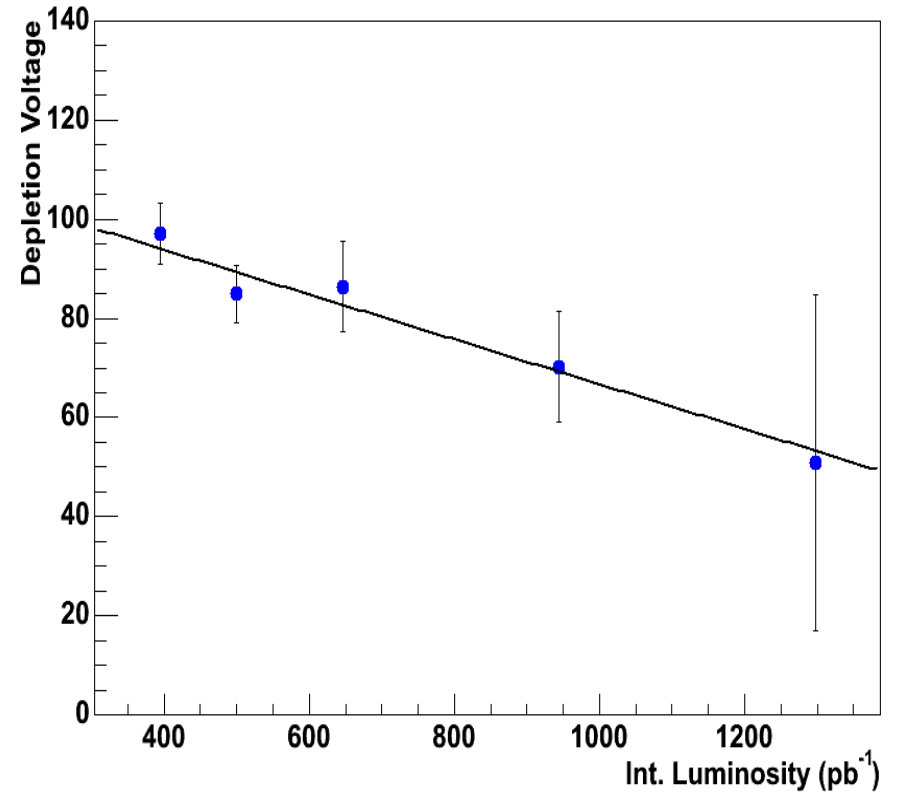


## SVX Ladder From Innermost Layer



Data set  $1.8 \text{ fb}^{-1}$

## L00 Ladder from Innermost Radius



Data set  $1.3 \text{ fb}^{-1}$

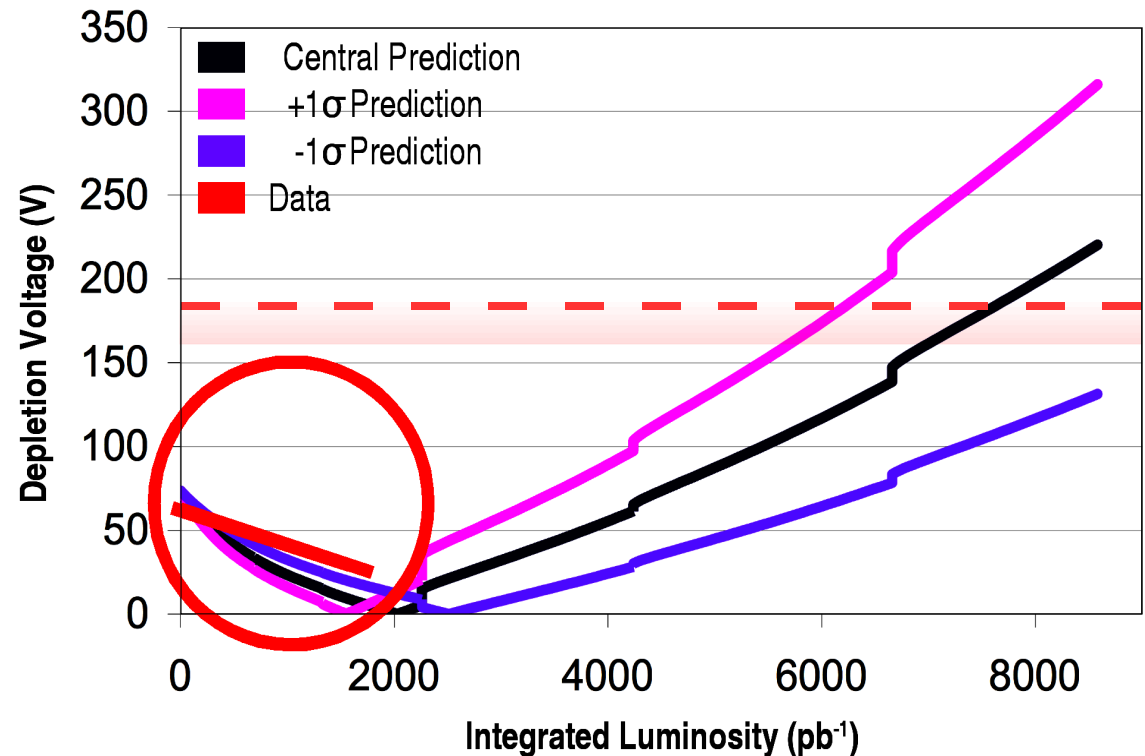




# CDF Results



- Expect L0 of SVX-II to be the first layer which cannot be fully depleted
- L0 of SVX-II has not inverted yet, type inversion is expected around  $2.9 \text{ fb}^{-1}$
- Extrapolation of current status assuming similar slopes before and after inversion: L0 of SVX will outlast Run-II



Prediction: S. Worm, "Lifetime of the CDF Run II Silicon," VERTEX 2003



# CDF: Bias Currents



- Leakage currents are expected to evolve linearly with integrated luminosity
- Use the measured bias currents to determine
  - Leakage currents
  - Radial damage profile
- Requires knowledge of the sensor temperature
- Make a model based prediction for S/N evolution over luminosity
- Study uses data set with  $95 \text{ pb}^{-1}$  (May/June 2004)
- Takes into account the exact beam positions to correct for off-center beam position (asymmetric radiation)



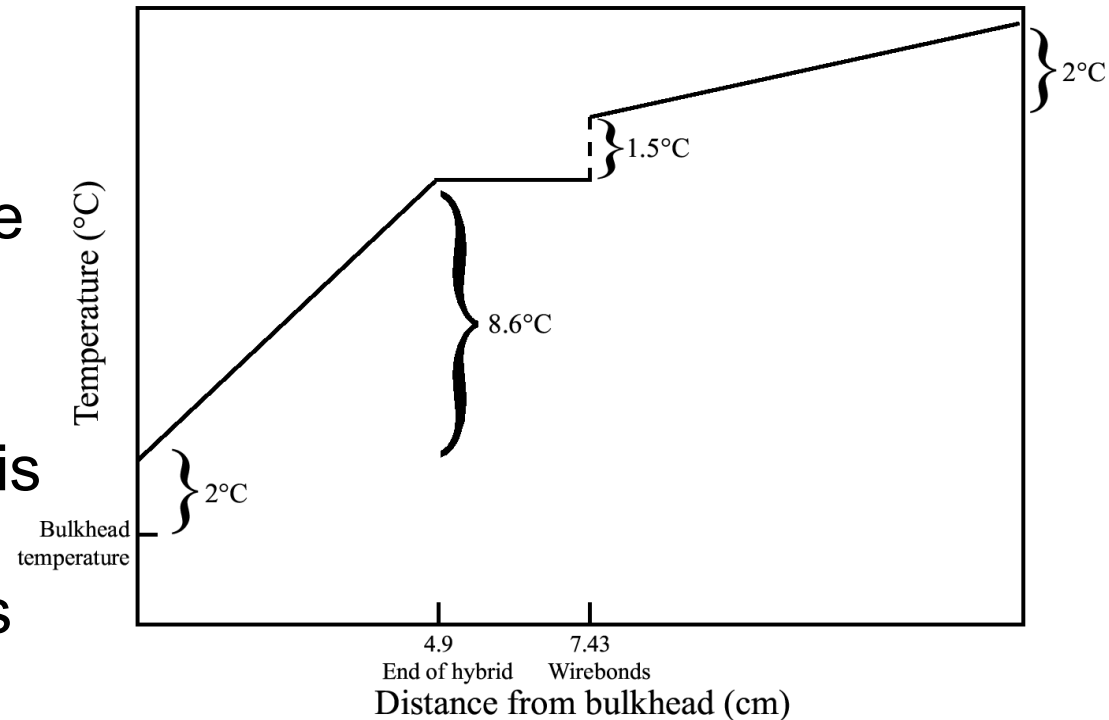
# CDF Temperature Modeling



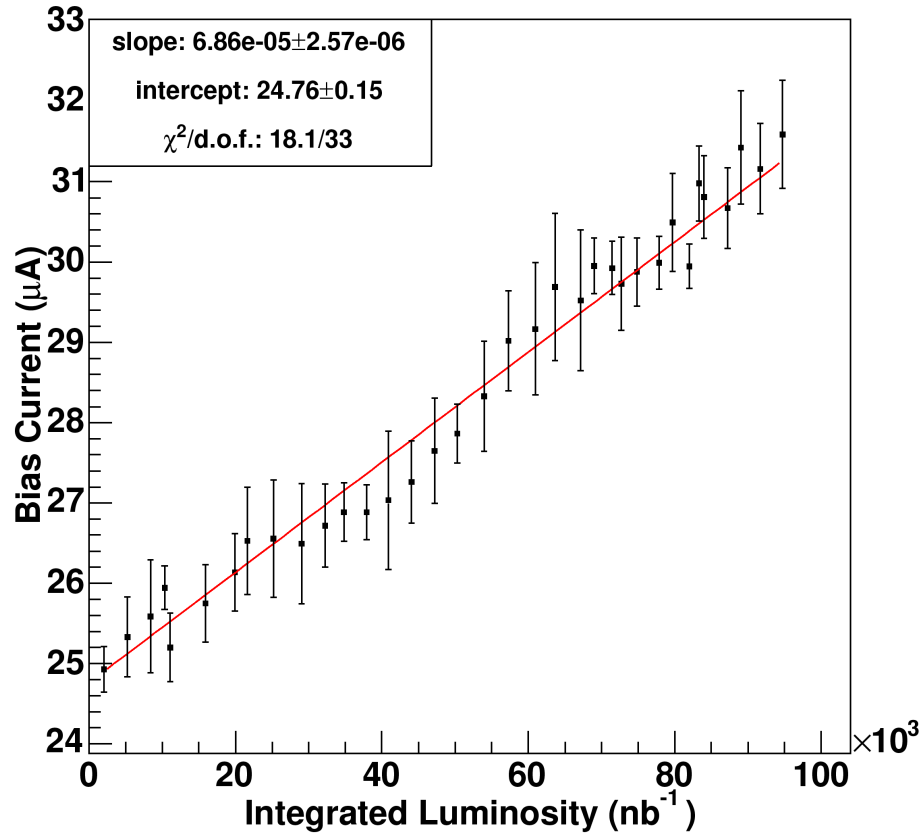
- The bias currents depend on the temperature

$$\frac{I_1}{I_2} = \left( \frac{T_2}{T_1} \right)^2 \cdot e^{\frac{-E}{2k_B} \left( \frac{T_2 - T_1}{T_2 \cdot T_1} \right)}$$

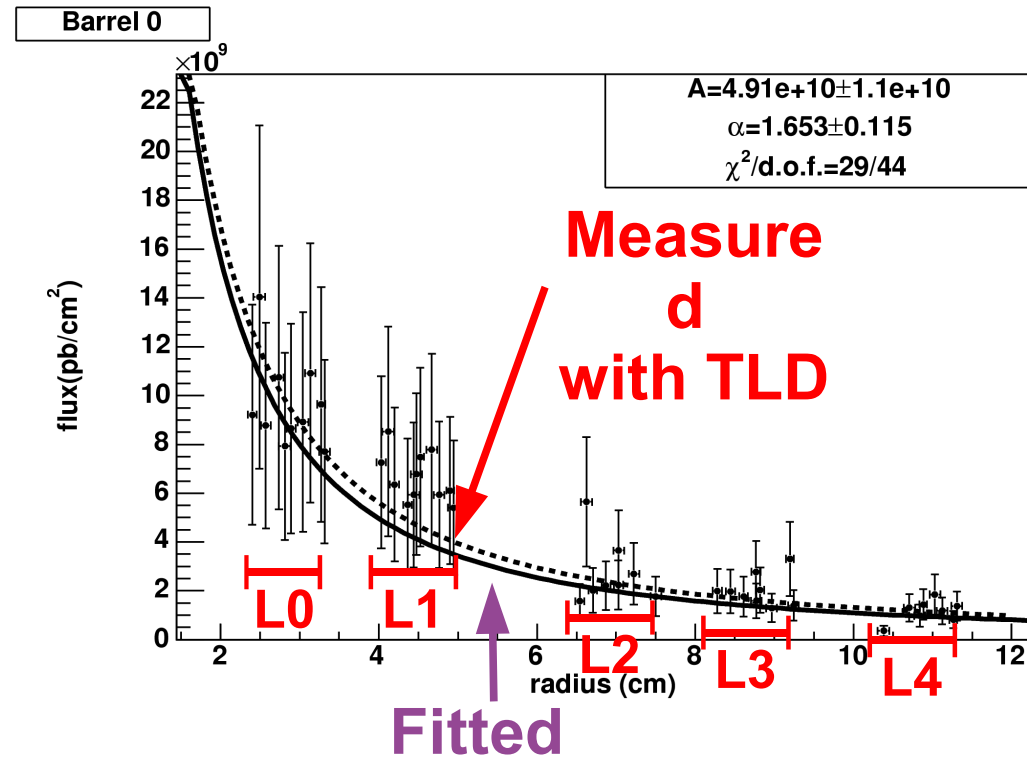
- However we cannot measure the temperature of the sensors directly
- Rely of finite element analysis modeling of the sensors, leading to large uncertainties
- This is the dominating systematic effect



# CDF Results



Bias current shows expected linear dependence



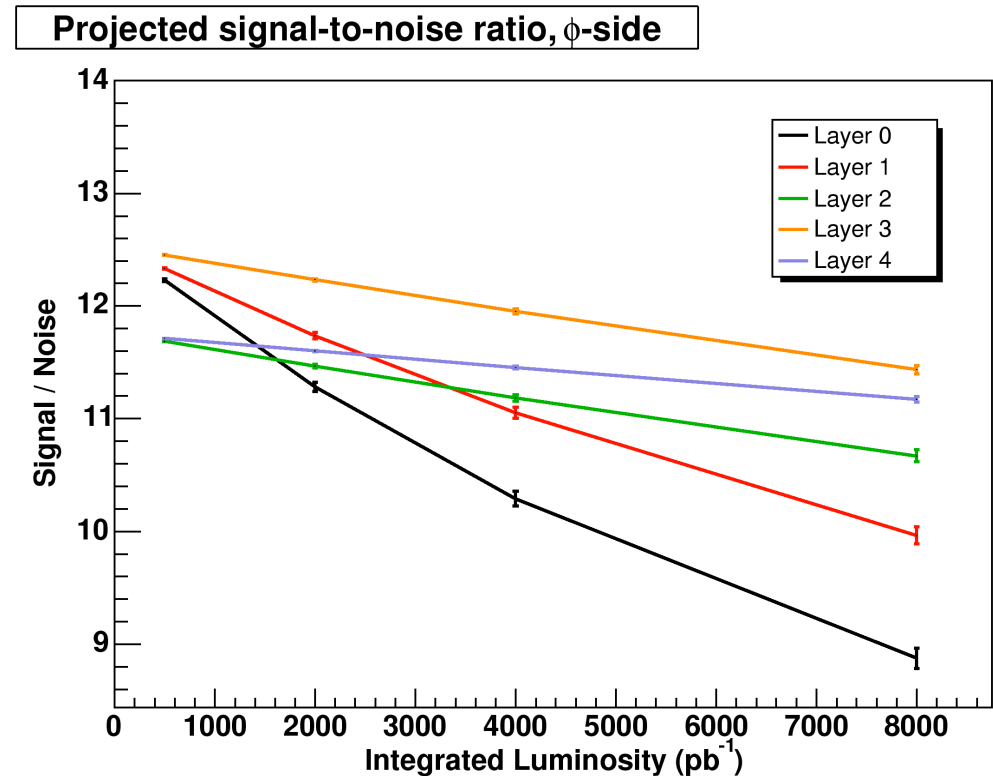
Flux shows expected radial dependence



# CDF S/N Predictions



- Prediction uses
  - Shot noise (Dominant source)
  - Chip Noise
- Shot noise
  - Assume  $I_{\text{Bias}} \sim I_{\text{Leakage}}$
  - $Q_{\text{shot}} = k \sqrt{I_{\text{Leakage}}}$
- Chip Noise
  - $Q_{\text{chip}} = f_1(\Phi_{\text{Dose}}) C_{\text{Chip}} + f_2(\Phi_{\text{Dose}})$
  - 7 % Noise Increase per Mrad
- Model does not include signal degradation





# CDF S/N Measurements



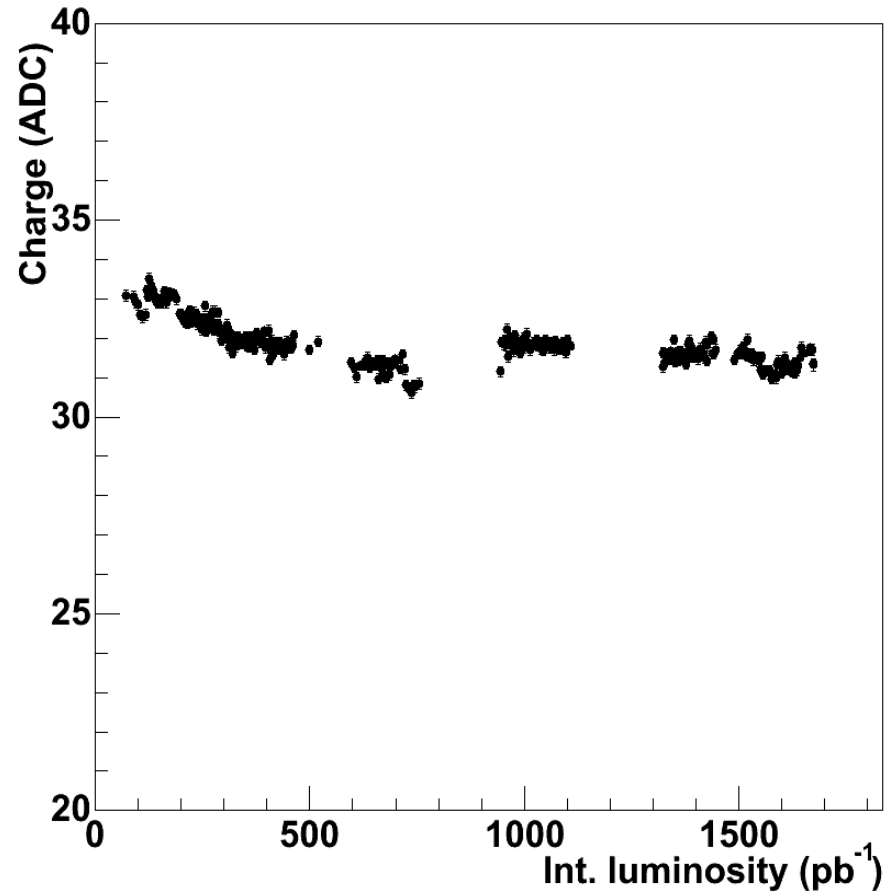
- Idea : Derive S/N measurement from data.
- Using J/ψ di-muon data.
  - Signal is defined as path-corrected charge sum of cluster using hits on tracks
  - Noise is defined as the single channel noise
  - Calculate S/N from these measurements
- Use entire Run-II data set (1.7 fb<sup>-1</sup> delivered)



# CDF Signal & Noise

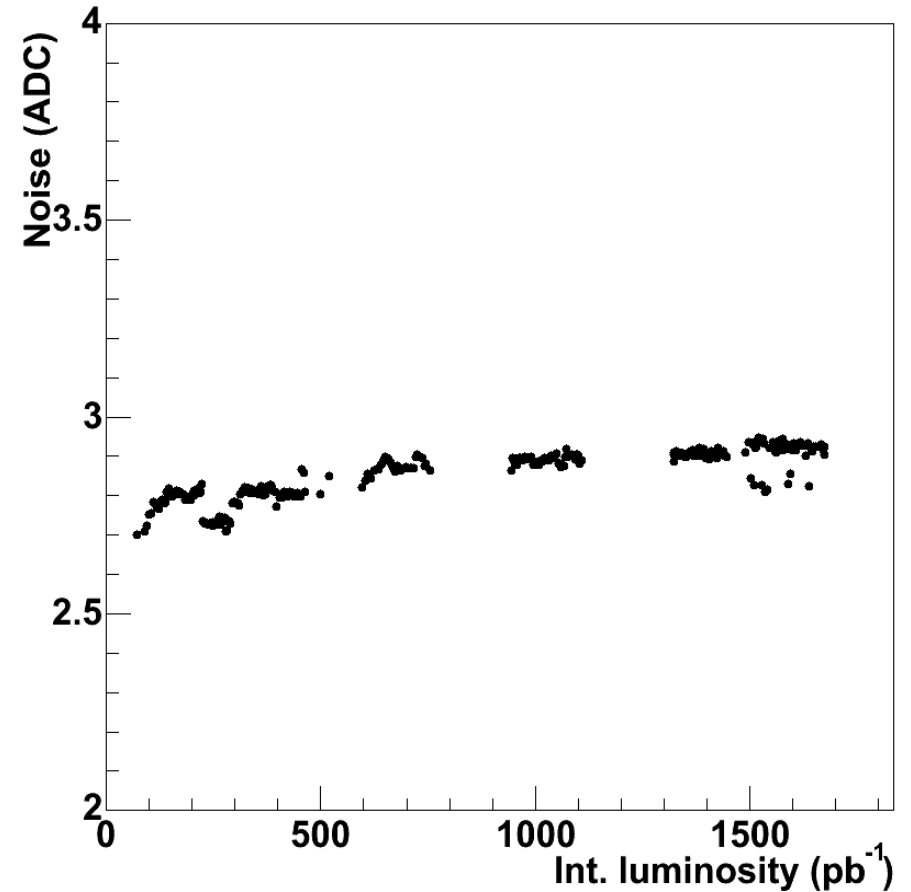


Charge  $\Phi$  vs integrated luminosity



Signal in SVX-II Layer 1

Noise  $\Phi$  vs integrated luminosity

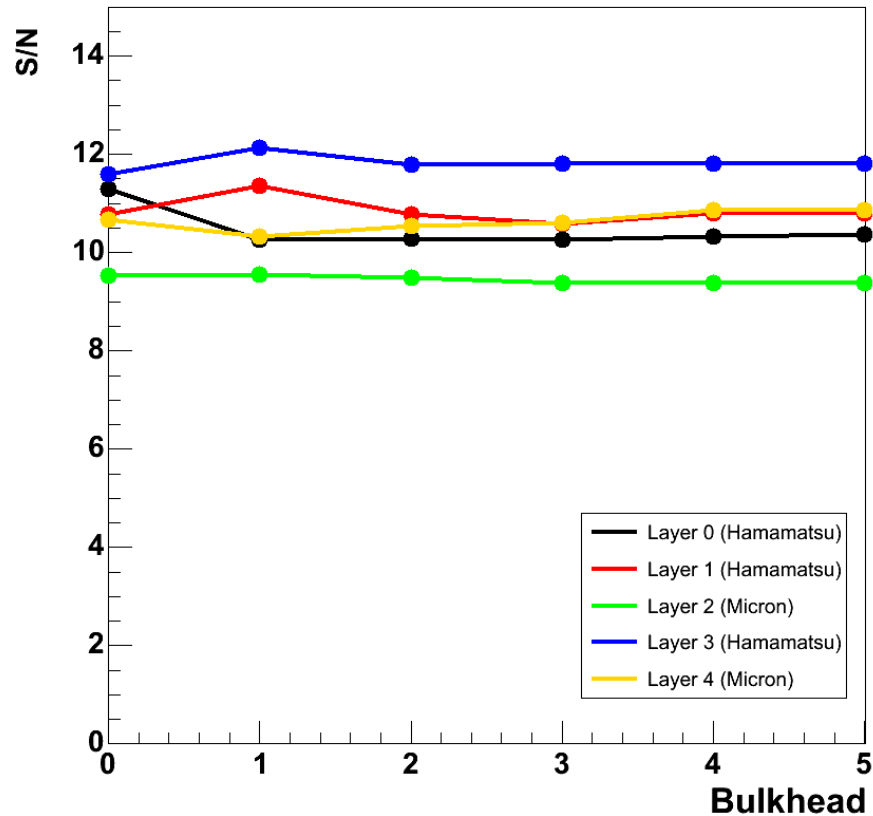


Noise in SVX-II Layer 1

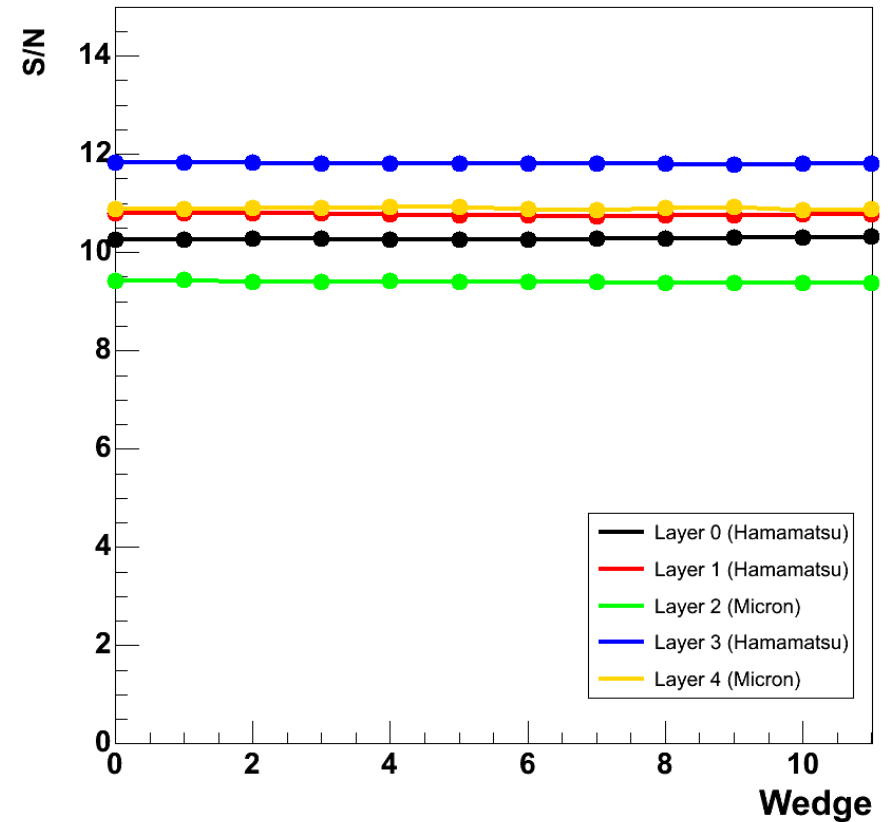
# CDF $\Phi/Z$ Dependence



SVX-II S/N  $\Phi$  Bulkhead 1675 pb<sup>-1</sup>



SVX-II S/N  $\Phi$  Wedge 1675 pb<sup>-1</sup>



Uniform detector performance



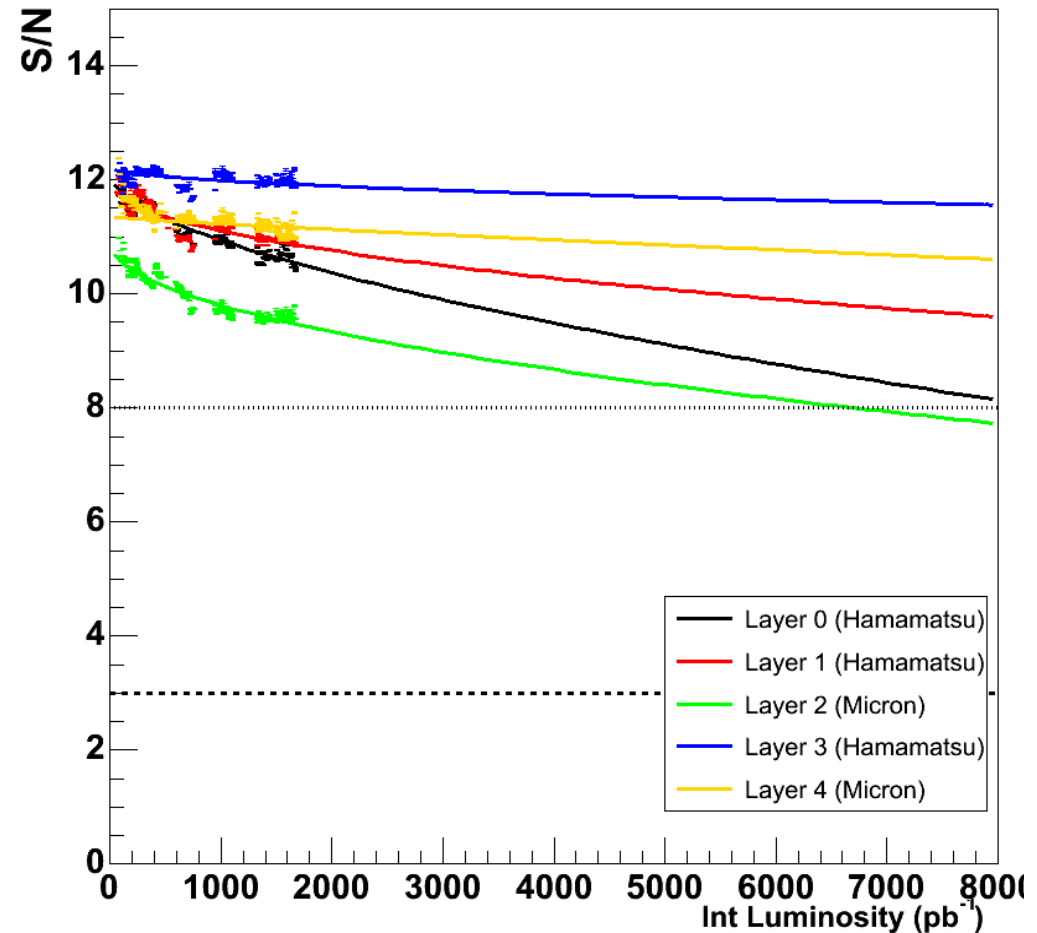


# CDF S/N Projections



- Excluded the first  $164 \text{ pb}^{-1}$  (Commissioning Phase)
- Simple model for luminosity dependence
  - Signal decreases linearly
  - Noise increase with square-root
- Use model to make projections from  $1.7 \text{ fb}^{-1}$  to  $8 \text{ fb}^{-1}$
- Work in progress

SVX-II S/N Projection  $\Phi$





# CDF Summary

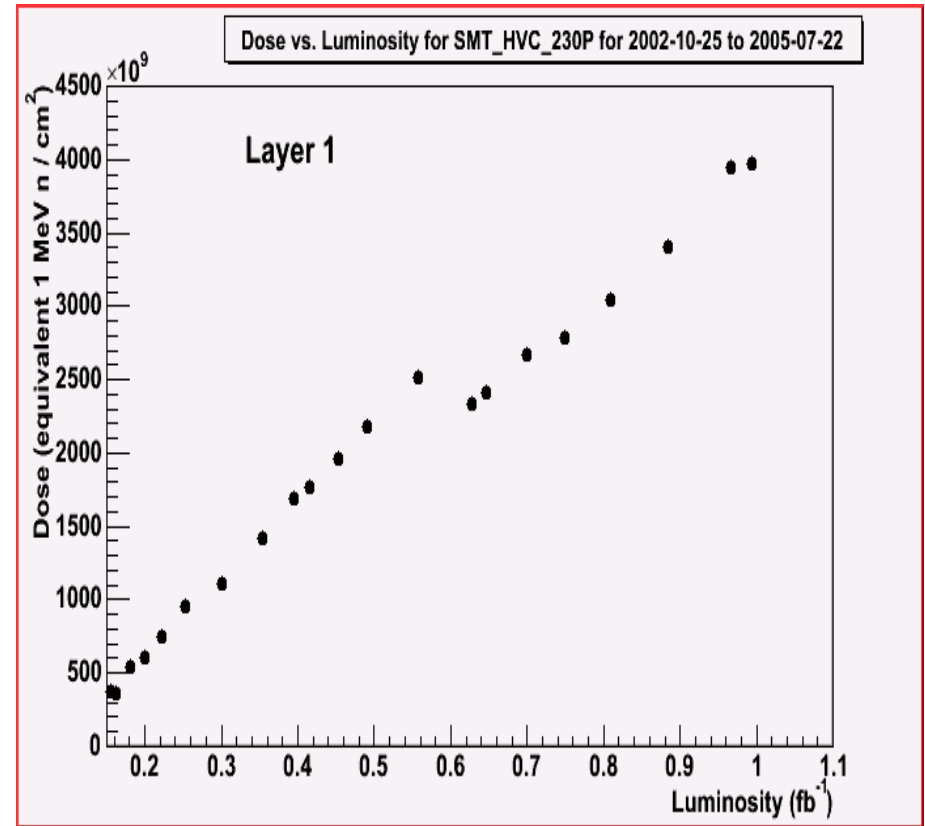
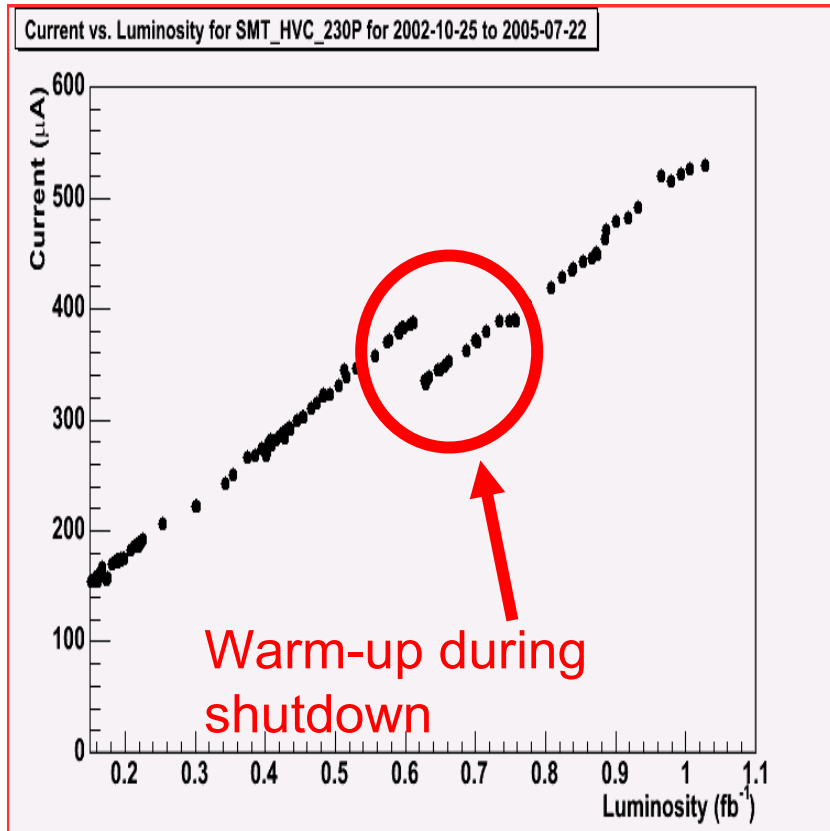


Several independent measurements indicate, that the detector behaves as expected.

Assuming no changes in behavior

- Depletion voltage: Current projections indicate, that detector can be fully depleted throughout Run-II
- Bias current monitoring
  - Measured flux agrees with TLD measurements
  - S/N prediction indicates no problems
- S/N measurements
  - No problems expected with S/N up to  $8 \text{ fb}^{-1}$
  - Very good agreement of predictions for Hamamatsu sensors

# DØ Bias Current Studies



Derive the dose from the bias current measurements

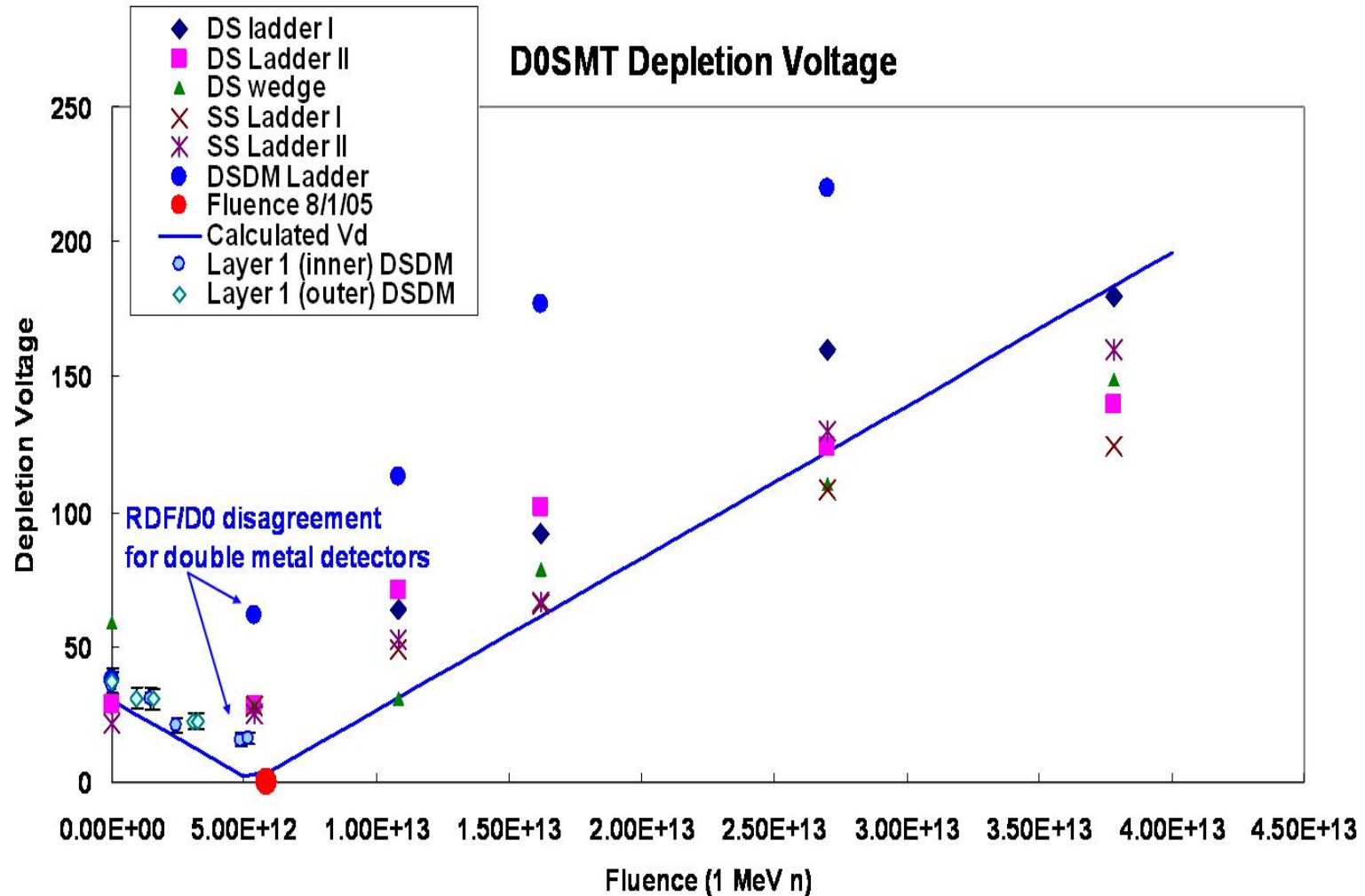


# DØ Dose Measurement Using The Booster

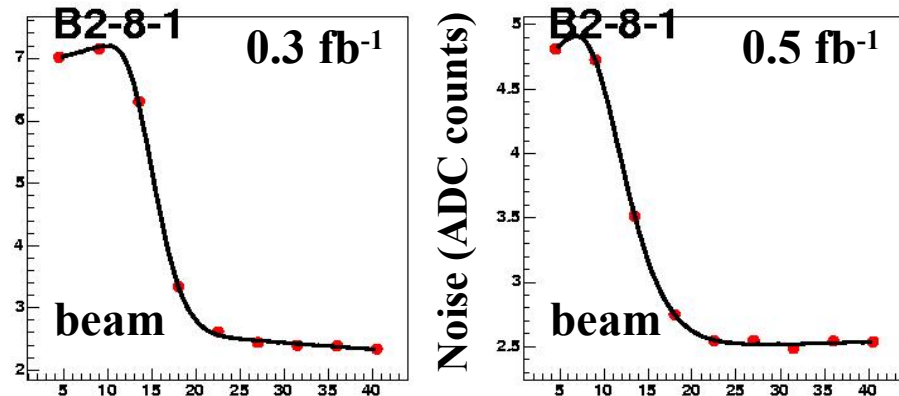


- Use Fermilab's 8 GeV “Proton Booster” to irradiate several SMT ladders
- Measure a depletion voltage as a function of the received dose
- Derive actual dose in the detector using the bias current measurement
- Compared the depletion voltage from the Booster with the depletion voltage from the bias scans

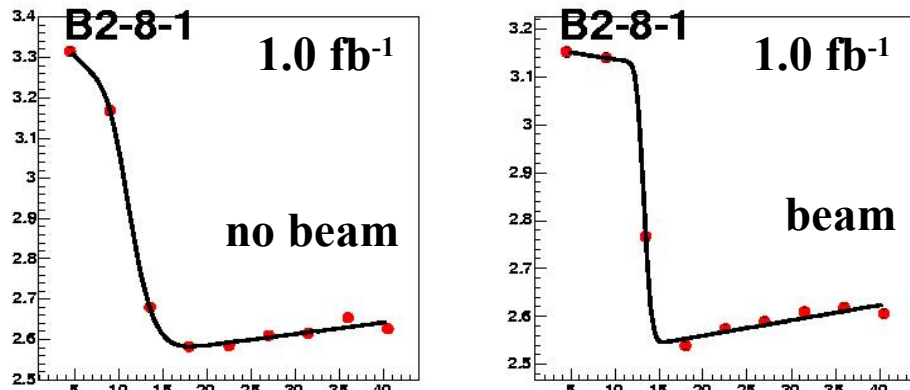
# DØ Booster Measurement



## Noise Scan

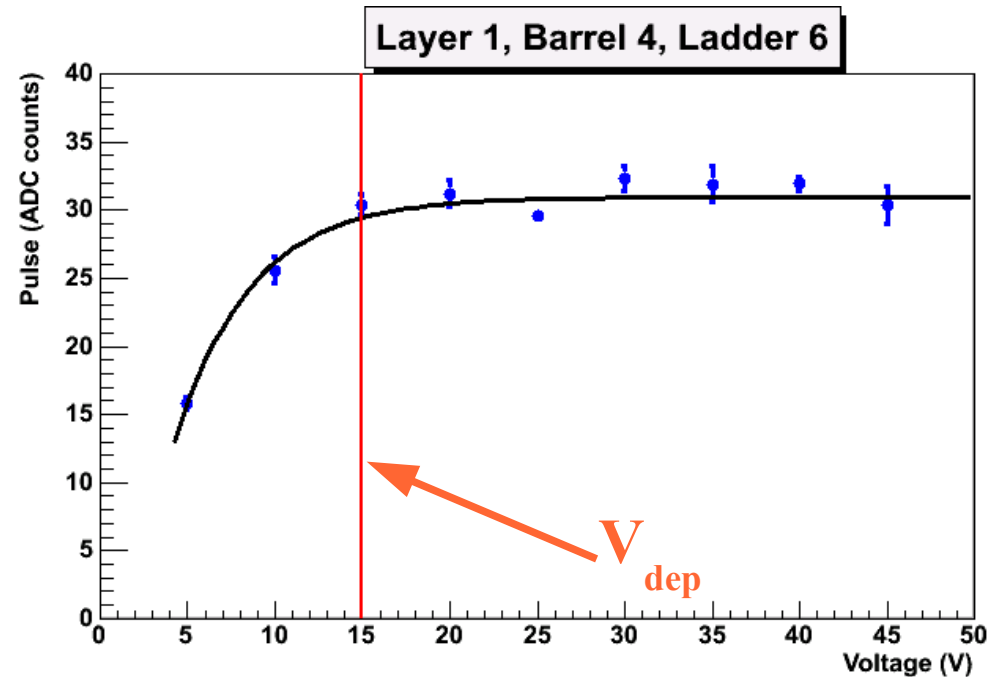


Layer 4 (DS)



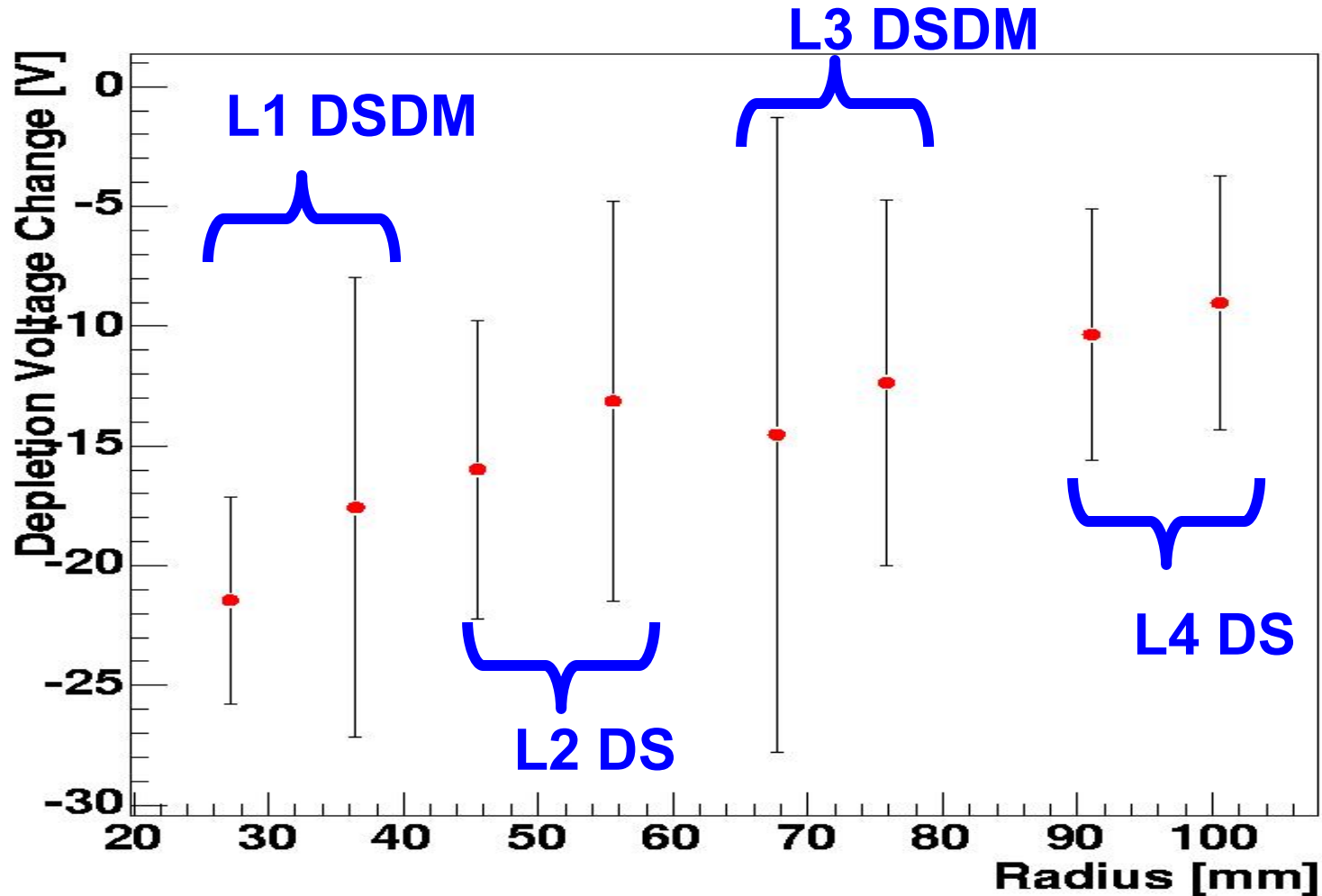
Voltage (V)

## Signal Scan

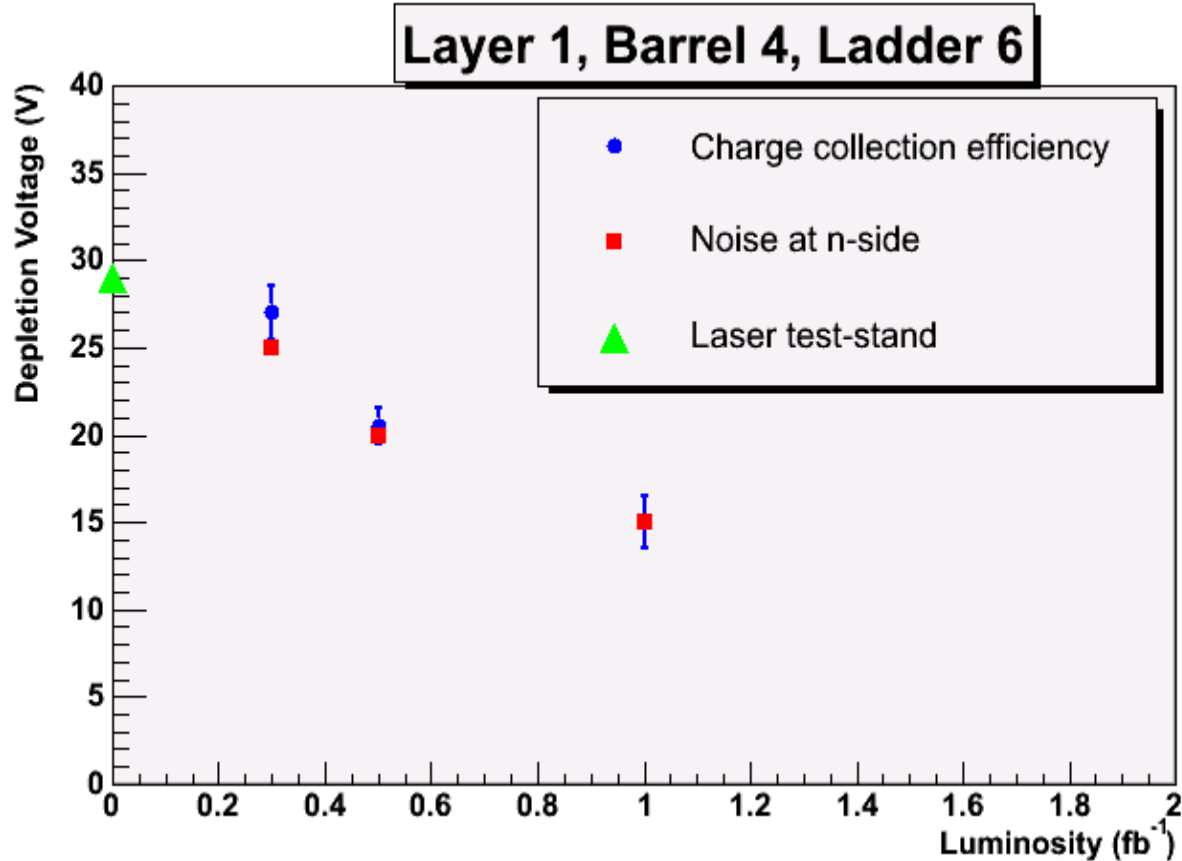


Both methods are very similar to CDF's

# DØ Depletion Voltage Changes

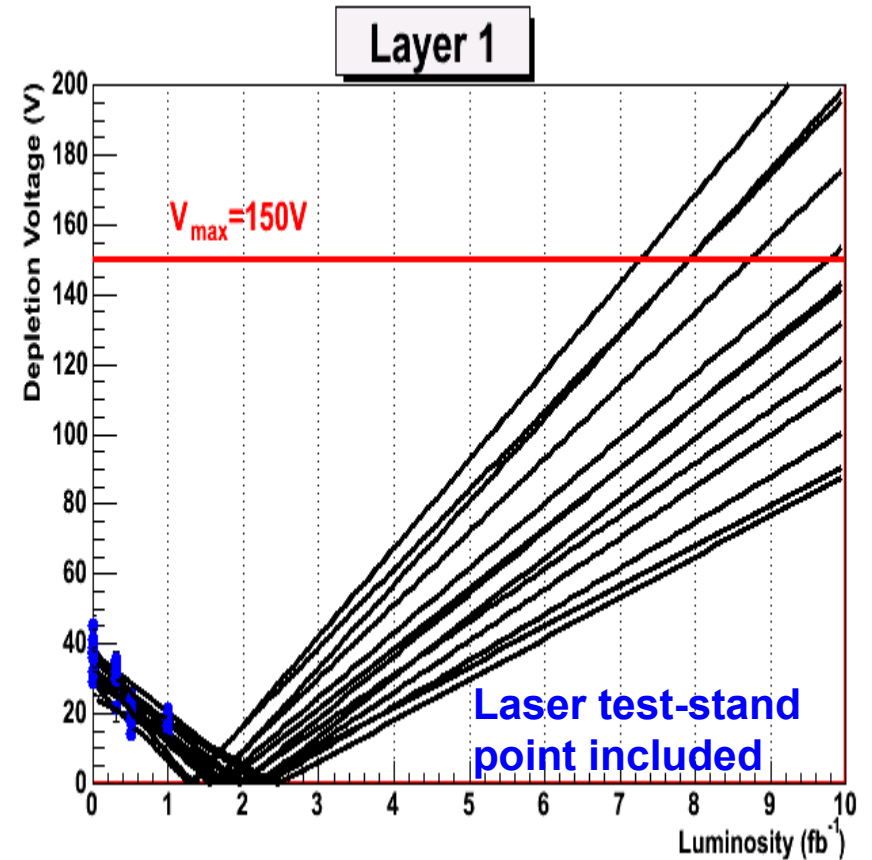
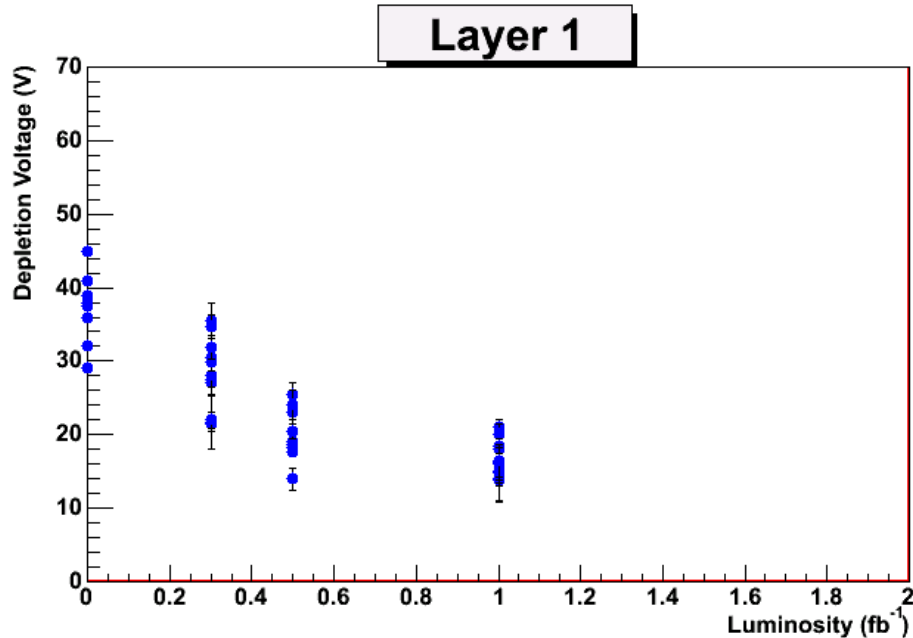


# DØ Bias Scans Comparison



Both signal and noise scan are in good agreement





- Inversion point: 1.5-3 fb<sup>-1</sup>
- Assuming the same magnitude slope after inversion point
  - $V_{dep} \sim V_{max} = 150V$  at delivered luminosity above 7 fb<sup>-1</sup>



# DØ Summary



The DØ shows the expected behavior.

Extrapolating from this:

- Depletion voltage studies indicate
  - Layer 1 will last for  $5-7 \text{ fb}^{-1}$
  - Layer 0 is designed to compensate a potential degradation of Layer 1
- Bias current measurements
  - Derive dose and comparison with results from Booster irradiation
  - Results are consistent with the bias scan results



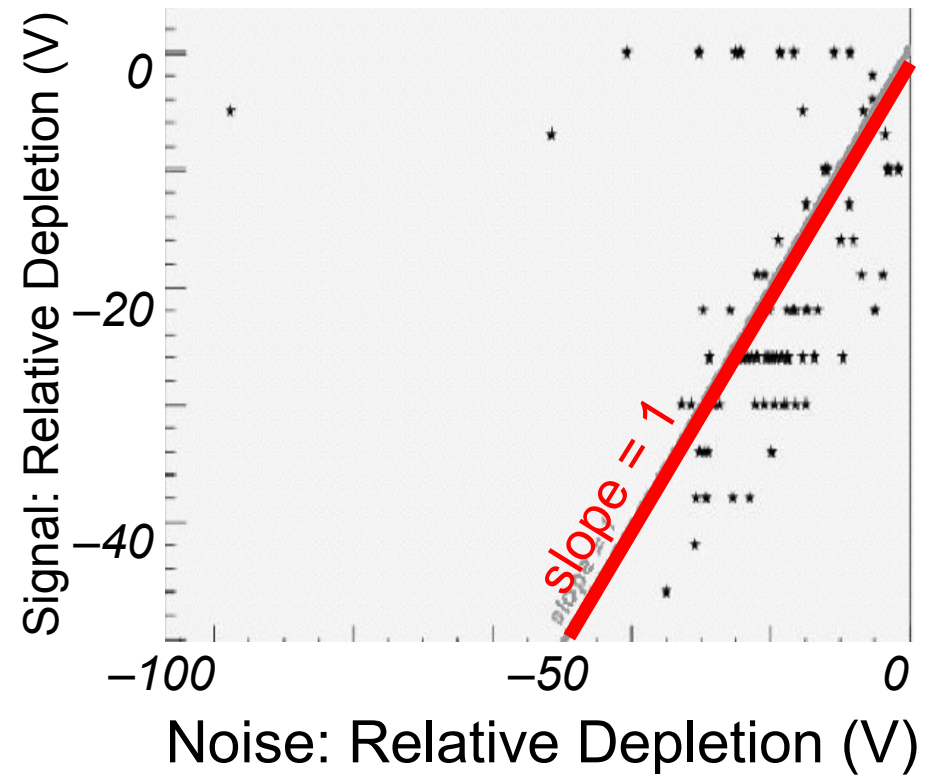
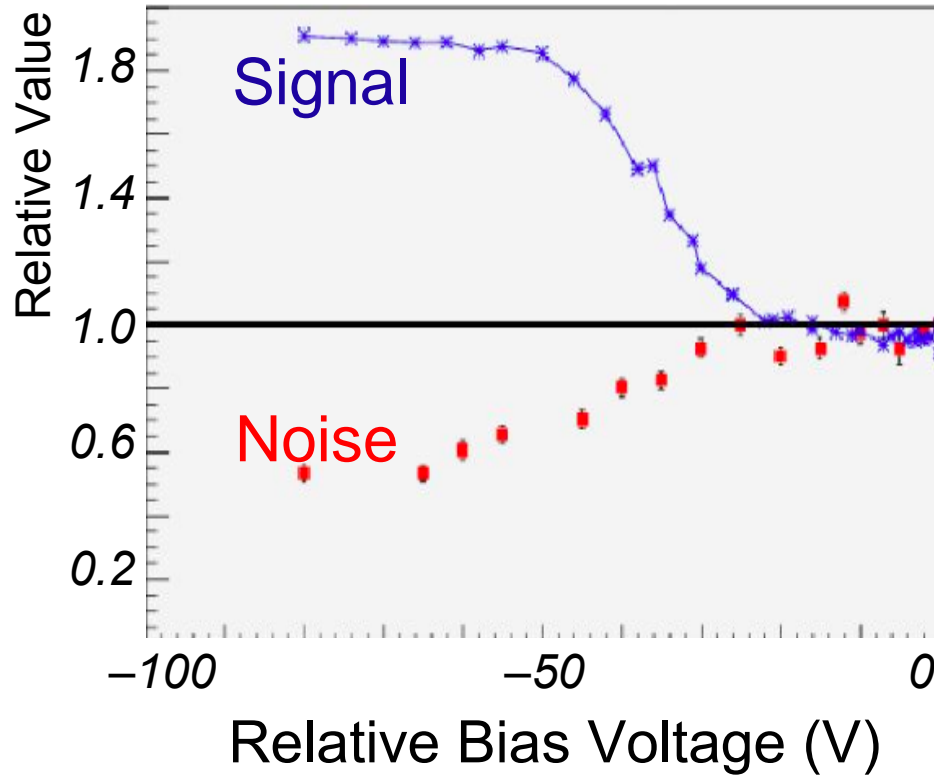
# Summary



- Both detectors are performing well
- Radiation measurements show both detector show expected behavior
- Projections indicate that the CDF silicon detector will survive up to  $8 \text{ fb}^{-1}$
- Projections indicate that the DØ silicon detector will survive up to  $8 \text{ fb}^{-1}$  except L1, which will last for  $5\text{-}7 \text{ fb}^{-1}$
- Both detectors are likely to invert soon
- Continuous monitoring will show if the current trend continues
- A big thanks to my CDF and DØ colleagues for helping to prepare this talk



# CDF Bias Scan Comparison





# Bias current definitions



- Leakage current:
  - current measured through a PN junction when the junction is reverse biased. (can be related to materials science measurements of other diode structures).
- Bias current:
  - current measured through a semiconductor sensor when a potential difference is placed across the sensor. (includes effects of guard rings, etc).